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Abstract of the Disclosure

[0048] A structure for reinforcing or anchoring a bond pad on a chip. The structure includes a bonding pad provided in a dielectric layer, at least one conductive layer provided beneath and in electrical contact with the bonding pad, and at least one parallel-interconnect anchor structure provided in contact with the bonding pad and the conductive layer. The anchor structure or structures prevent the bonding pad from exerting excessive force against the dielectric layer and cracking the dielectric layer when the chip is subjected to physical testing. The bonding pad may have truncated or curved corners, for example.